



PATENTS  
112055-0040P1  
17732-38560.001

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re The Application of: )  
David Chong Sook Lim et al. )  
Serial No.: 10/664,982 )  
Filed: September 17, 2003 )  
For: PACKAGING SYSTEM FOR )  
DIE-UP CONNECTION OF A )  
DIE-DOWN ORIENTED INTE- )  
GRATED CIRCUIT )  
Examiner: Leonardo Andujar  
Art Unit: 2826  
Cesari and McKenna, LLP  
88 Black Falcon Avenue  
Boston, MA 02210  
September 23, 2005

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**SUPPLEMENTAL AMENDMENT**

In response to the Office action dated 05/20/2005, please enter the following supplemental amendments: